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PATENT APPLICATION

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE
TECHNOLOGY CENTER

In re the Application of

Kazuo TANAKA

Group Art Unit: 2811

Application No.: 09/586,963

Examiner: C. Nguyen

Filed: June 5, 2000

Docket No.: 039894.01

For: A SEMICONDUCTOR DEVICE AND A METHOD FOR MAKING THE SAME
THAT PROVIDE ARRANGEMENT OF A CONNECTING REGION FOR AN
EXTERNAL CONNECTING TERMINAL (AS AMENDED)

* 11/C

11-20-01

T. Flowers

SUPPLEMENTAL AMENDMENT UNDER 37 C.F.R. §1.115

Director of the U.S. Patent and Trademark Office
Washington, D.C. 20231

Sir:

In further reply to the Office Action mailed May 3, 2001, and further to the October 4
personal interview, please amend the above-identified application as follows:

IN THE CLAIMS:

Please replace claim 2 as follows:

- Sub
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2. (Three Times Amended) A semiconductor device having a multiple wiring
layer structure, comprising:
- a first conductive layer connected to a conductive member for external
connection;
 - a second conductive layer disposed below said first conductive layer, the
second conductive layer having a plurality of openings;
 - a third conductive layer disposed below said second conductive layer;
 - a first insulating interlayer disposed between said first conductive layer and
said second conductive layer;
- C1

at least one first through hole provided in said first insulating interlayer;
a fourth conductive layer filling said at least one first through hole;
a second insulating interlayer disposed between said second conductive layer
and said third conductive layer;

at least one second through hole provided in said second insulating interlayer
the said at least one first through hole disposed substantially directly above said at least one
second through hole; and

cont.
C1 a fifth conductive layer filling said at least one second through hole, wherein
said first insulating interlayer and said second insulating interlayer are connected to each
other through said openings of said second conductive layer, and a contiguous section of said
first insulating interlayer with said second insulating interlayer is, thereby, formed between
said first conductive layer and said third conductive layer.

REMARKS

Claims 2-8, 12-14 and 21 are pending. By this Supplemental Amendment, claim 2 is amended. Claims 4, 5, 7-11, 13, 14 and 21 have previously been withdrawn from consideration and claims 1, 9-11 and 15-20 have been canceled. Reconsideration based on the following remarks is earnestly requested.

Applicant appreciates the courtesies extended to Applicant's representative at the October 4 personal interview. The points discussed are incorporated into the following remarks.

The attached Appendix includes marked-up copy of the rewritten claim (37 C.F.R. §1.121(c)(1)(ii)).

Claim 2 has been amended in accordance with the discussions held at the personal interview. Thus, Applicant believes that the pending claims define patentable subject matter.